

**MMDT5401** 

### 150V DUAL PNP SMALL-SIGNAL TRANSISTOR IN SOT363

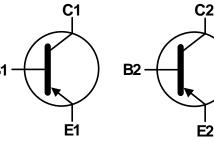
### **Features**

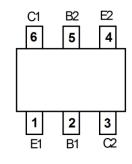
- Epitaxial Planar Die Construction
- Complementary NPN Type Available (MMDT5551)
- Ideal for Medium Power Amplification and Switching
- Ultra-Small Surface-Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An automotive-compliant part is available under separate datasheet (MMDT5401Q)

## **Mechanical Data**

- Package: SOT363
- Package Material: Molded Plastic, "Green" Molding Compound,
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 63
- Weight: 0.006 grams (Approximate)







Top View Device Symbol

Top View Pin-Out

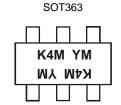
## Ordering Information (Note 4)

Part Number	Packago	Marking	Reel Size (inches)	Tape Width (mm)	Packing	
Fait Nullibei	Package	Warking	Reel Size (Illulies)	rape widin (ililii)	Qty.	Carrier
MMDT5401-7-F	SOT363	K4M	7	8	3,000	Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



K4M = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: K = 2023) M = Month (ex: 9 = September)

#### Date Code Key

Year	2003		2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	Р		K	L	М	N	Р	R	S	T	U	٧
				_				_				_
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



# **Absolute Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-160	V
Collector-Emitter Voltage	VCEO	-150	V
Emitter-Base Voltage	V <sub>EBO</sub>	-6	V
Continuous Collector Current	lc	-200	mA

# Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	D-	200	mW	
Power Dissipation	(Notes 6 & 7)	$P_D$	320		
Thermal Decistores Investiga to Ambient	(Note 5)	D	625		
Thermal Resistance, Junction to Ambient	(Notes 6 & 7)	Reja	390	°C/W	
Thermal Resistance, Junction to Case (Note 8)		R <sub>θJC</sub>	140		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS								
Collector-Base Breakdown Voltage	ВУсво	-160		_	٧	$I_C = -100\mu A$ , $I_E = 0$		
Collector-Emitter Breakdown Voltage (Note 9)	BVceo	-150	_	_	V	$I_C = -1 \text{mA}, I_B = 0$		
Emitter-Base Breakdown Voltage	ВУЕВО	-6	_	_	V	I <sub>E</sub> = -100μA, I <sub>C</sub> = 0		
Collector-Base Cutoff Current	1		_	-50	nA	V <sub>CB</sub> = -120V, I <sub>E</sub> = 0		
Collector-base Cutoff Current	Ісво		_	-50	μΑ	V <sub>CB</sub> = -120V, I <sub>E</sub> = 0, T <sub>A</sub> = +100°C		
Base-Emitter Cutoff Current	I <sub>EBO</sub>		_	-50	nA	V <sub>EB</sub> = -5V, I <sub>C</sub> = 0		
ON CHARACTERISTICS (Note 9)								
		50		_		Ic = -1mA, $VcE = -5V$		
DC Current Gain	hFE	60	_	240	_	Ic = -10mA, VcE = -5V		
		50		_		Ic = -50mA, VcE = -5V		
Collector-Emitter Saturation Voltage	V			-0.2	V	Ic = -10mA, I <sub>B</sub> = -1mA		
Collector-Entitler Saturation Voltage	V <sub>CE(sat)</sub>	_	_	-0.5	V	Ic = -50mA, I <sub>B</sub> = -5mA		
Door Emitter Seturation Voltage	.,		_	-1	V	Ic = -10mA, I <sub>B</sub> = -1mA		
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	_			V	Ic = -50mA, I <sub>B</sub> = -5mA		
SMALL-SIGNAL CHARACTERISTICS								
Output Capacitance	Cobo	_		6	pF	$V_{CB} = -10V$ , $f = 1MHz$ , $I_E = 0$		
Small Signal Current Gain	h <sub>fe</sub>	40		260		$I_C = -1 \text{mA}$ , $V_{CE} = -10 \text{V}$ , $f = 1 \text{MHz}$		
Current Gain-Bandwidth Product	f⊤	100		300	MHz	$I_C = -10$ mA, $V_{CE} = -10$ V, $f = 100$ MHz		
Noise Figure	NF	_	_	8	dB	$V_{CE}$ = -5V, $I_C$ = -200 $\mu$ A, Rs = 10 $\Omega$ , f = 1kHz		

Notes:

- 5. For a device mounted on minimum recommended pad layout 1oz weight copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 6. Same as Note 5, except the device is mounted 25mm X 25mm 2oz copper.
- 7. Maximum combined dissipation.
- 8. Thermal resistance from junction to the top of package.
- 9. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



# Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

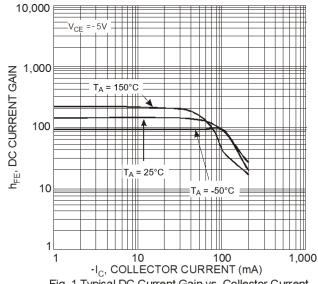
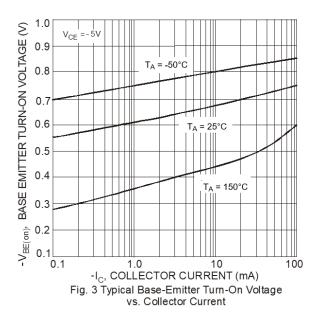


Fig. 1 Typical DC Current Gain vs. Collector Current



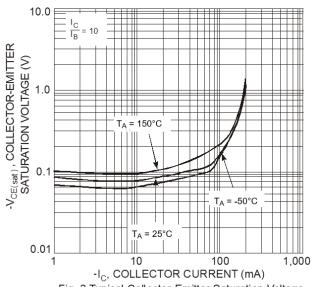


Fig. 2 Typical Collector-Emitter Saturation Voltage vs. Collector Current

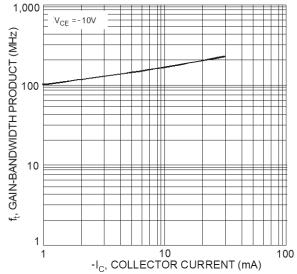


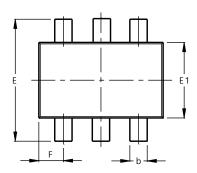
Fig. 4 Typical Gain-Bandwidth Product vs Collector Current

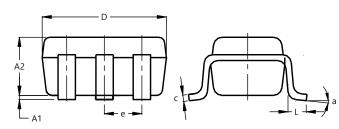


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT363**



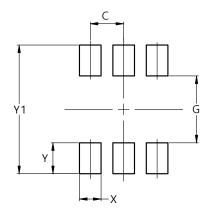


SOT363							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.10	0.30	0.25				
C	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	0.650 BSC						
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All Dimensions in mm							

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### **SOT363**



Dimensions	Value			
Dillielisiolis	(in mm)			
С	0.650			
G	1.300			
Х	0.420			
Υ	0.600			
Y1	2.500			

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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MMDT5401 5 of 5

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